EPISTAR

ES-EABCS09B

InGaN S-series LED Chip

> Mechanical Specification:

(1) Dimension

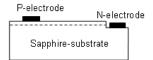
- Chip size: 9 mil x 45 mil (225 \pm 25 μ m x 1143 \pm 25 μ m)

- Thickness: 5.1 mil (130 \pm 10 μ m) - P bonding pad: 2.4 mil (60 \pm 10 μ m) - N bonding pad: 2.4 mil (60 \pm 10 μ m)

(2) Metallization

Topside P electrode: Au alloyTopside N electrode: Au alloy





Features:

- · High radiant flux
- · 100% probing test
- · Passivation layer on top
- Long operation life

Applications:

Backlighting

> Electro-optical Characteristics at 25°C: (1)

Parameter	Symbol		Condition	Min.	Тур.	Max.	Unit
Forward Voltage	Vf1		If = 10μA	2.0	-	-	V
	Vf2		If = 20mA	-	2.8	2.9	V
Reverse Current	Ir		Vr = 5V	-	-	2.0	μΑ
Dominant Wavelength ⁽²⁾	λd		If = 20mA	445	-	465	nm
Spectra Half-width	Δλ		If = 20mA	-	25	-	nm
Radiant Flux ⁽³⁾⁽⁴⁾	Ро	A38	- If = 20mA	44	-	46	mW
		A39		46	-	48	

Note:

⁽¹⁾ ESD protection during chip handling is recommended.

⁽²⁾ Basically, the wavelength span is 20nm; however, customers' special requirements are also welcome.

⁽³⁾ Radiant flux is determined by using an Ag-plated TO-can header without an encapsulant.

⁽⁴⁾ Radiant flux measurement allows a tolerance of $\pm 15\%$.

> Absolute Maximum Ratings:

Parameter	Symbol	Condition	Rating	Unit
Forward DC Current	If	Ta = 25°C	≤ 60	mA
Reverse Voltage	Vr	Ta = 25°C	≤ 5	V
Junction Temperature	Tj	-	≤ 125	°C
		Chip	-40 ~ +85	°C
Storage Temperature	Tstg	Chip-on-tape/storage	5 ~ 35	°C
		Chip-on-tape/transportation	-20 ~ +65	°C
Temperature during Packaging	-	-	280(<10sec)	°C

Note: Maximum ratings are package dependent. The above maximum ratings were determined using a Printed Circuit Board (PCB) without an encapsulant. Stresses in excess of the absolute maximum ratings such as forward current and junction temperature may cause damage to the LED.

> Characteristic Curves:

Fig.1 – Relative luminous Intensity vs. Forward Current

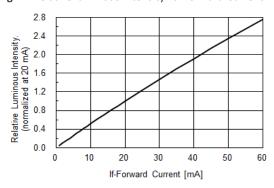


Fig.3 – Relative Intensity (@20mA) vs. Ambient Temperature

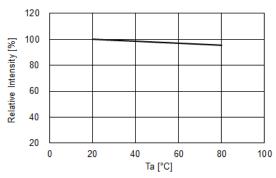


Fig.5 – Dominant Wavelength (@20mA) vs. Ambient Temperature

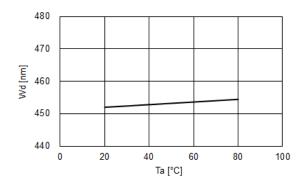


Fig.2 - Forward Current vs. Forward Voltage

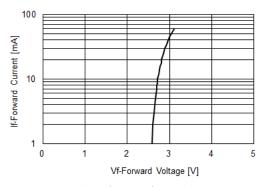


Fig.4 – Forward Voltage (@20mA) vs. Ambient Temperature

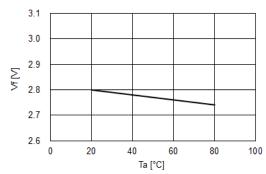


Fig.6 – Maximum Driving Forward DC Current vs. Ambient Temperature (De-rating based on Tj max. = 125°C)

